

TSMC-01-1693



April 16, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/785,524 02/24/04 |
Kuen-Chyr Lee et al.

A METHOD FOR IMPROVING THE ELECTRICAL
CONTINUITY FOR A SILICON-GERMANIUM
FILM ACROSS A SILICON/OXIDE/POLY-
SILICON SURFACE USING A NOVEL TWO-
TEMPERATURE PROCESS

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on April 26, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date Stephen B. Ackerman 4/26/04

U.S. Patent 6,346,453 to Kovacic et al., "Method of Producing a Si-Ge Base Heterojunction Bipolar Device," describes a method for making an HBT using a sacrificial layer over a Si-Ge layer to protect an area for where an emitter is later formed.

U.S. Patent 5,523,243 to Mohammad, "Method of Fabricating a Triple Heterojunction Bipolar Transistor," describes a method for making a triple HBT by forming a Si/Si-Ge superlattice for the base and a second superlattice for the emitter.

U.S. Patent 5,256,550 to Laderman et al., "Fabricating a Semiconductor Device with Strained Si_{1-x}Ge_x Layer," describes a method for forming a strained Si_{1-x}Ge_x layer for the base of a bipolar transistor to improve the emitter injection efficiency.

U.S. Patent 6,251,738 to Huang, "Process for Forming a Silicon-Germanium Base of Heterojunction Bipolar Transistor," describes a method for making a Si-Ge base on a mesa and then removing the Si-Ge adjacent to the mesa.

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U.S. Patent 5,951,757 to Dubbelday et al., "Method for Making Silicon Germanium Alloy and Electric Device Structures," describes a semiconductor structure which comprises at least one relaxed SiGe buffer formed on a silicon-on-insulator (SOI) substrate.

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761

